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a. Serial No.	f. Foreign Priority	k. Print Claim(s)	(p. PTO-1449)
b. Applicant(s)	g. Disclaimer	I. Print Fig.	q. PTOL-85b
c. Continuing Data	h. Microfiche Appendix	m. Searched Column	r. Abstract
d. PCT	i. Title	n. PTO-270/328	s. Sheets/Figs
e. Domestic Priority	j. Claims Allowed	o. PTO-892	t. Other

SPECIFICATION	
1	MESSAGE
a. Page Missing	PTO 1449 - Please either initial or line
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LIST OF	REFE	RENCES CITED BY A	PPLICANT		ATTY. DOCKET NO. 100970.665047US1		SERIAL N 10/026135		
A se deta	di Logi:				APPLICANT Pedigo, Jesse et at				
^	3 24				FILING DATE 20 December 2001		GROUP To be determined		
\$	LIST OF REFERENCES CITED BY APPLICANT  SO SANGER PROCESS If necessary)  DOCUMENTS  DOCUMENTS  DOCUMENT NAMEER DATE  AA 6,454,154 09/24/02 Filling D  Method Slurry  CC 4,498,275 02/12/85 Rotary F  DD  EE  FF  GG HH  II  DOREIGN PATENT DOCUMENTS  DOCUMENT NAMEER DATE  JJ  KK  LL  MM  NN  SHER REFERENCES (Including Author, Title, Date, Pertinent Pages, Etc.)  OO								
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	M	6,454,154	09/24/02	Filling Device		228	33	12/28/00	
	ВВ	5,893,404	04/13/99	Fabrication Utilizin	ratus for Metal Solid Freeform ng Partially Solidified Metal	164	71.1	09/20/96	
	СС	4,498,275	02/12/85	Rotary Filling and	Capping Apparatus	53	506	07/06/81	
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10,026, 135 100665.0047US2 LIST OF REFERENCES CITED BY APPLICANTO I P AMERICAN Jesse Pedigo, et al APR 0 8 2002 2 RECEIVED HEAT, DATE READENMENT TRADELINE 12-20-01 APR 0 9 2002

U.S. PATENT DOCUMENTS		

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T COSS -	tearly NOV No. 1 N.C. Nobel M	livit	N489.	(Tana)	in 14-1, 144	PROPERTY I	
15	3,601,523	08-24-71	Through Hule Connectors	174	68.5	06/19/70	
	4,106,187	08/15/78	Curved Rigid Printed Circuit Boards	29	625	G1/16/76	
	4,283,243	08/11/81	Use of Photosensitive Stratum to Create Through-Hule Connections in Circuit Boards	156	237	03/20/80	
	4,360,570	11/23/82	Use of Photosensitive Stratum to Create Through-Hole Connections in Circuit Boards	428	596	06/15/81	
	4,622,239	11/11/86	Method and Apparatus for Dispensing Viscous  Materials	427	96	02/18/86	
	4,700,474	10:20:87	Apparatus and Method for Temporarily Scaling Holes in Printed Circuit Boards	29	846	11/26/85	
	4,777,721	10/18/88	Apparatus and Method for Temporarily Sealing Holes in Primed Circuit Boards Utilizing a Thermodeformable Material	29	846	10/15/87	
	4,783,247	11/8/88	Method and Manufacture for Electrically Insulating  Base Material Used in Plated-Through Printed Circuit  Panels	204	181.1	05/15/86	
	4,884,337	12/05/89	Method for Temporarily Scaling Isules in Printed Circuit Boards Utilizing a Thermodeformable Material	29	846	10/15/87	
	4,954,313	09/04/90	Method and Apparatus for Filling High Density Vias	419	9	02/03/89	
	4,964,948	10/23/90	Printed Circuit Board Through Hole Technique	156	659	11/13/89	
	4,995,941	02/26/91	Method of Manufacture Interconnect Device	156	630	05/15/89	
	5,053,921	10-01/91	Multilayer Interconnect Device and Method of Manufacture Thereof	361	386	10/23/90	
	5,058,265	10/22/91	Method for Packaging a Board of Electronic Components	29	852	09/10/90	
$\top$	5,117,069	05/26/92	Circuit Board Fabrication	174	261	09:28:90	
11	5,133,120	07/28/92	Method of Filling Conductive Material into Through Holes of Printed Wiring Board	29	852	03/15/91	
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	5,220,723	96-22-93	Process for Preparing Multi-Layer Printed Wiring Board	29	830	11:04:91	
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